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Signed. Semben E. Bertavin, Reg. No. 27 769

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s):Lu et al.

Serial No.: 08/977,407

Filed: November 24, 1997

For: ELECTRONIC SURFACE MOUNT

PACKAGE

Examiner: Mai, A.

Group Art Unit: 2832

Response to Office Action

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

This Response to Office Action is being submitted in response to the Office Action of September 8, 2000.

AMENDMENTS

IN THE CLAIMS:

1. An electronic surface mount package for mounting onto a printed circuit board comprising: a one piece construction package having a side wall and an open bottom,

a plurality of toroid transformers within said package, said toroid transformers each having wires wrapped thereon,

a plurality of terminal pins molded within and extending through and below a bottom of said side wall, one end of each of said pins having a notched solder post upon which said wires from said transformers are wrapped and soldered thereon, respectively,